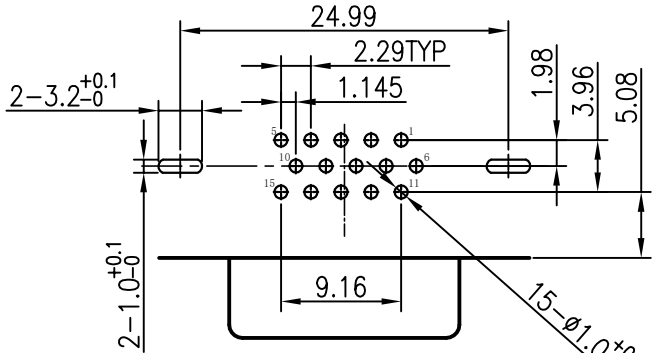
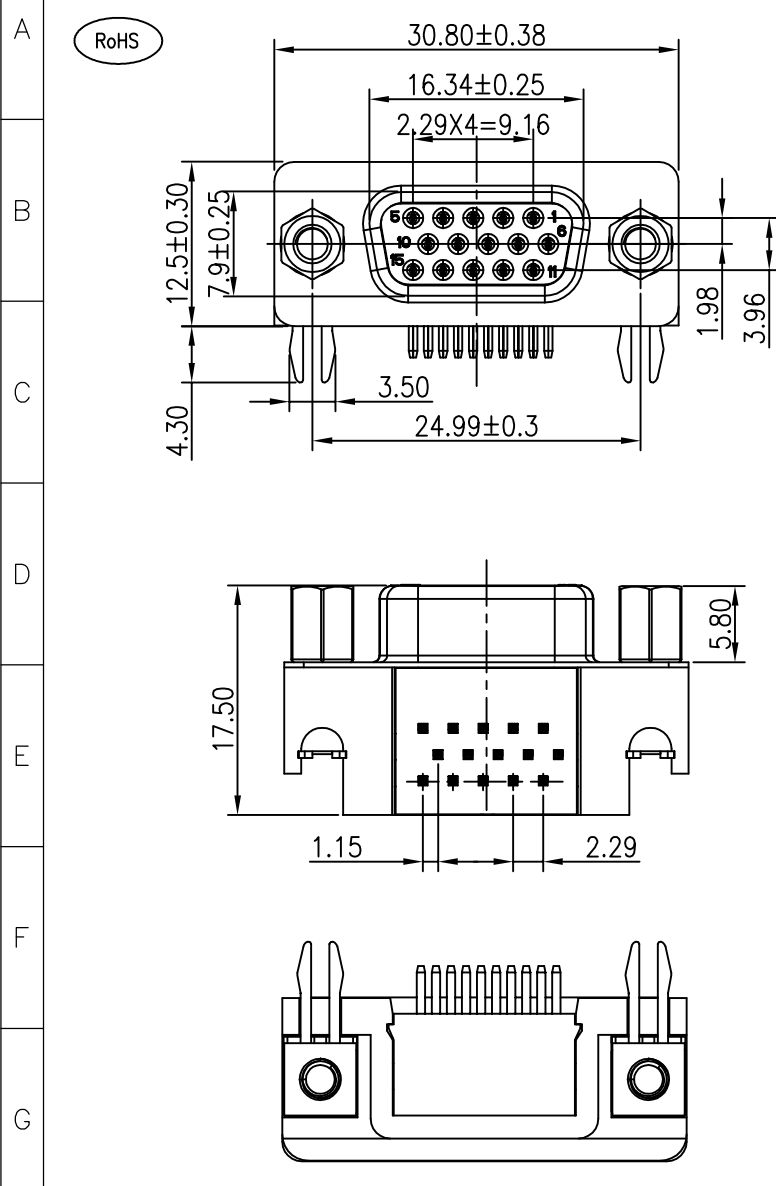
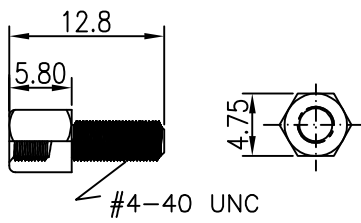
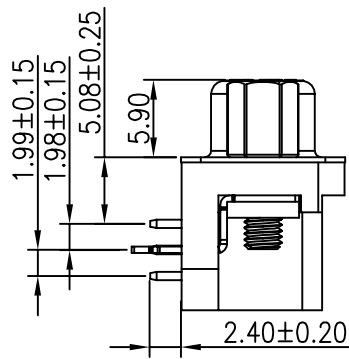


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements



RECOMMENDED PCB LAYOUT
RECOMMEND PCB THICKNESS:t1.6mm



- NOTE:
- 1.MATERIAL:
 - 1.1 INSULATOR:PBT+30%GF, UL94V-0, COLOR:BLUE
 - 1.2 COVER:PBT+30%GF, UL94V-0, COLOR::BLUE
 - 1.3 CONTACT: COPPER ALLOY,
 - 1.4 SHELL:SPCC
 - 1.5 HARPOON:SPCC
 - 1.6 SCREW:SPCC
 - 1.7 RIVET:COPPER ALLOY,
 2. PLATING:
 - 2.1 CONTACT: SELECTIVE GOLD PLATED ON CONTACT AREA 80u" Min. MATTE TIN PLATED ON SOLDER TAIL 50u" Min. NICKEL UNDER-PLATED
 - 2.2 SHELL:50u" Min, NICKEL PLATED OVERALL
 - 2.3 HARPOON:MATTE TIN PLATED OVERALL
 - 2.4 SCREW:NICKEL PLATED OVERALL
 - 2.5 RIVET:NICKEL PLATED OVERALL
 3. SPECIFICATIONS:
 - VOLTAGE: 250 VAC(RMS) MAX.
 - CURRENT RATING: 3 AMPERE PER CONTACT
 - CONTACT RESISTANCE: 30 MILLIOHMS MAX.
 - INSULATION RESISTANCE: 5000 MEGOHMS MIN.
 - DIELECTRIC WITHSTANDING VOLTAGE: 1000V AC(RMS)
 - MATING FORCE: 5.1Kg.Max.
 - UNMATING FORCE:1.0Kg.Min.
 - OPERATING TEMPERATURE:-25? ~ +85?

P/N: WLDBF9-15 1 X X 0 129

PLATING: 1-G/F COLOUR: G-BLUE

H	REV.		REVISION RECORD		DATE			GENERAL TOLERANCES		SCALE: 1:1		NAME		DATE		PART.NO:		DWG.NO:		 WanLian Teconology Co., Ltd		H			
	AO		NEW RELEASE		21.01.13			LINEAR		ANGLES		APPROVED		Wang_jr		21.01.13		WLDBF9-151XX0129					ENDE05		
								0.0±0.35		X°REF±6°		DESIGNER		Han_Gao		21.01.13									
							UNIT:mm		0.00±0.25		X°±3°		DRAWN		Zijun_Huang		21.01.13		TITLE: HDR5.08 15F 90°DIP 铆锁		REV: AO		SHEET: 1/1		
							SIZE: A4		0.000±0.10		X°X' ±2°														
1			2			3			4			5			6			7			8				